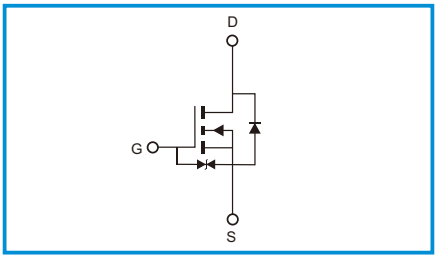
N-Channel Mosfet



Features

- Lead Free Product is Acquired
- Surface Mount Package
- N-Channel Switch with Low R_{DS}(on)
- Operated at Low Logic Level Gate Drive
- Marking:KF or R1B

Functional Diagram



Applications

- Load/Power Switching
- Interfacing Switching
- Battery Management for Ultra Small Portable Electronics
- Logic Level Shift

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$MAX	I_D
20V	380mΩ@4.5V	0.75A
	450mΩ@2.5V	
	800mΩ@1.8V	

Maximum Ratings (Ta=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Typical Gate-Source Voltage	V_{GS}	±12	V
Continuous Drain Current (note 1)	I_D	0.75	A
Pulsed Drain Current (t_p=10μs)	I_{DM}	1.8	A
Power Dissipation (note 1)	P_D	150	mW
Thermal Resistance from Junction to Ambient (note 1)	$R_{\theta JA}$	833	℃/W
Operation Junction and Storage Temperature Range	T_J,T_{STG}	-55~+150	℃
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T_L	260	℃

Electrical Characteristics (Ta=25°C unless otherwise specified)

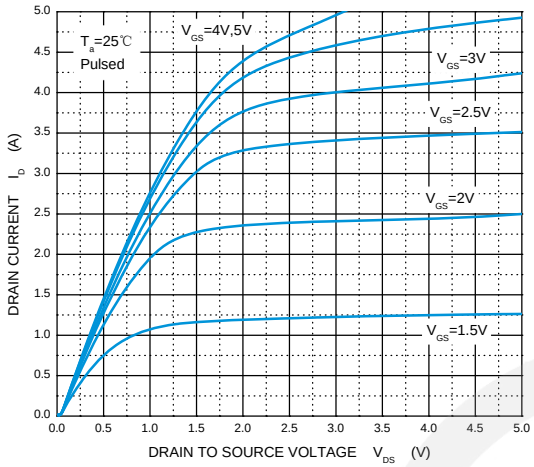
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D =250μA	20			V
Zero gate voltage drain current	I_{DSS}	V_{DS} =20V,V_{GS} = 0V			1	μA
Gate-body leakage current	I_{GSS}	V_{GS} =±10V, V_{DS} = 0V			±20	μA
Gate threshold voltage (note 2)	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =250μA	0.35	0.54	1.1	V
Drain-source on-resistance (note 2)	$R_{DS(on)}$	V_{GS} =4.5V, I_D =0.65A		270	380	mΩ
		V_{GS} =2.5V, I_D =0.55A		320	450	mΩ
		V_{GS} =1.8V, I_D =0.45A		390	800	mΩ
Forward transconductance (note 2)	g_{FS}	V_{DS} =10V, I_D =0.8A		1.6		S
Diode forward voltage	V_{SD}	I_S=0.15A, V_{GS} = 0V			1.2	V
DYNAMIC CHARACTERISTICS (note 4)						
Input capacitance	C_{iss}	V_{DS} =16V,V_{GS} =0V,f =1MHz		79	120	pF
Output capacitance	C_{oss}			13	20	pF
Reverse transfer capacitance	C_{rss}			9	15	pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time (note 3)	$t_{d(on)}$	V_{GS}=4.5V,V_{DS}=10V, I_D =500mA,R_{GEN}=10Ω		6.7		ns
Turn-on rise time (note 3)	t_r			4.8		ns
Turn-off delay time (note3)	$t_{d(off)}$			17.3		ns
Turn-off fall time (note 3)	t_f			7.4		ns
Total Gate Charge (note 3)	Q_g	V_{DS} =10V,V_{GS} =4.5V,I_D =0.25A		750		pC
Gate-Source Charge (note 3)	Q_{gs}			75		pC
Gate-Drain Charge (note 3)	Q_{gd}			225		pC

Notes :

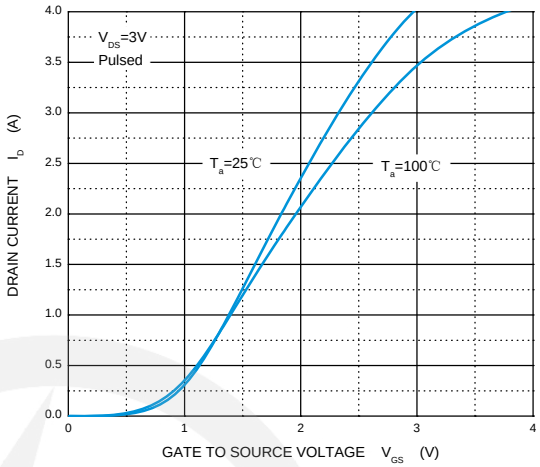
1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse Width=300μs, Duty Cycle=2%.
3. Switching characteristics are independent of operating junction temperatures.
4. Guaranteed by design, not subject to producting.

Typical Characteristics

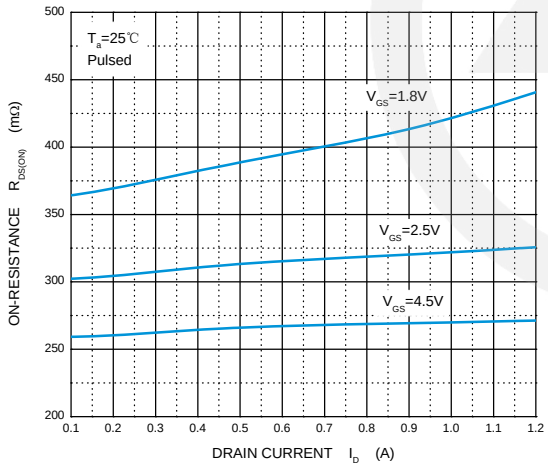
Output Characteristics



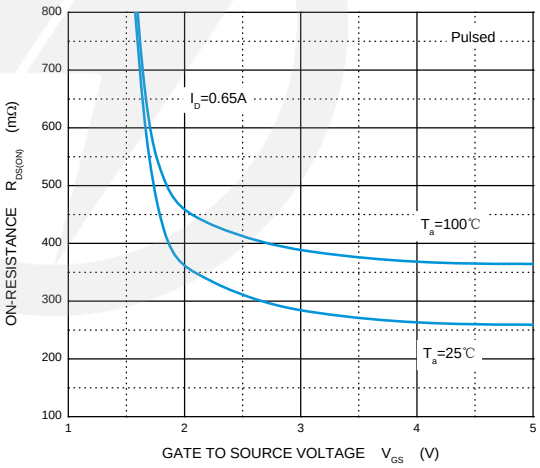
Transfer Characteristics



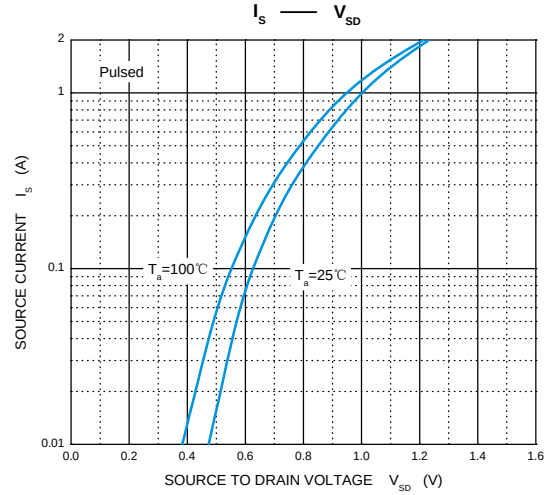
$R_{DS(ON)}$ —— I_D



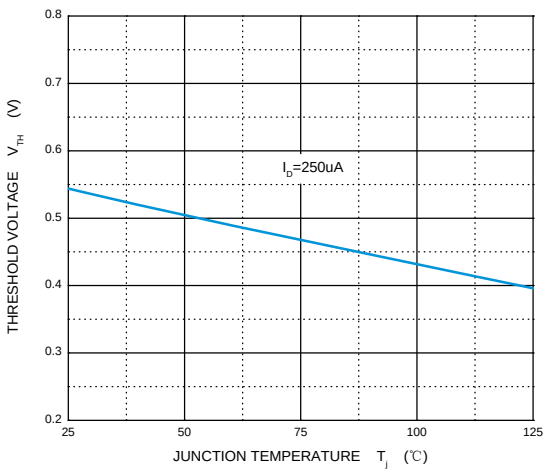
$R_{DS(ON)}$ —— V_{GS}



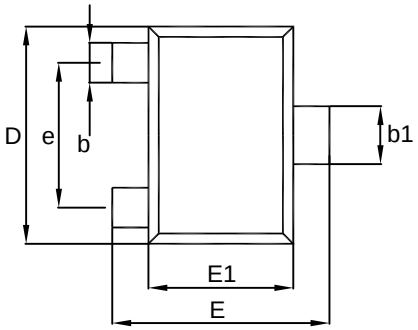
I_S —— V_{SD}



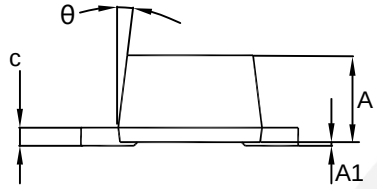
Threshold Voltage



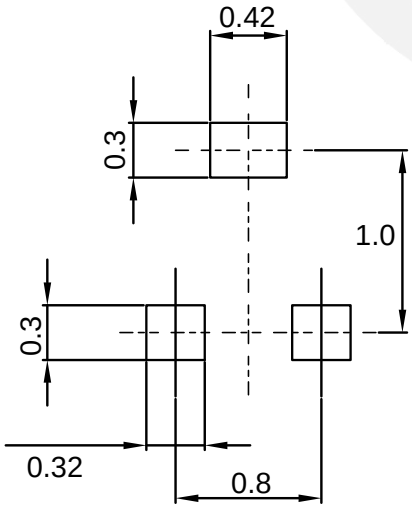
SOT-723 Package Outline



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	0.430	0.500
A1	0.000	0.050
b	0.170	0.270
b1	0.270	0.370
c	0.080	0.150
D	1.150	1.250
E	1.150	1.250
E1	0.750	0.850
e	0.800TYP.	
θ	7° REF.	

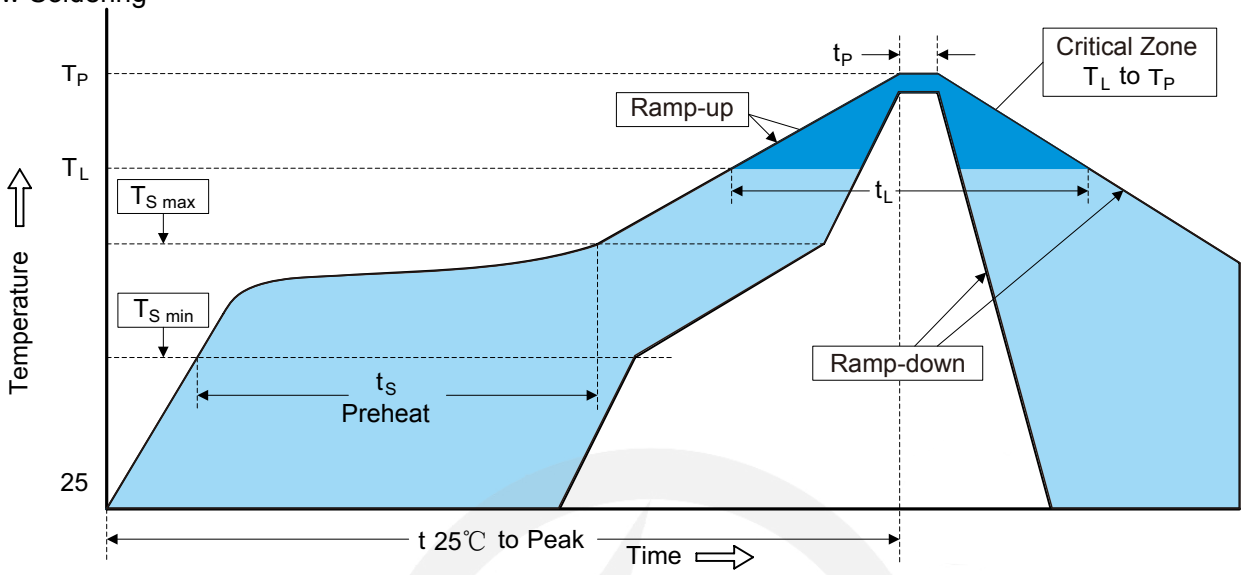


SOT-723 Suggested Pad Layout



Recommended Soldering Conditions

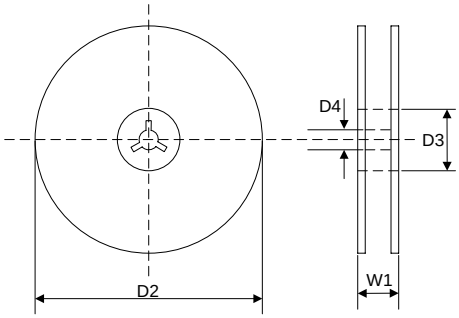
Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3℃/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_S)	 150℃ 200℃ 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	 3℃/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	 217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max.

7” Reel



D2	Φ178.0±2.0
D3	Φ50.0Min.
D4	Φ13.0±0.5
W1	16.0±2.0
Quantity: 8000PCS	